"PVD Deposition Process For
Enhanced Properties Of Metal Films"
Michael Rumer et al.
Appln. No.: 09/675,627

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FIG._1

**Effect of Power On Ti <0002>
Grain Orientation Performance**

FIG._2

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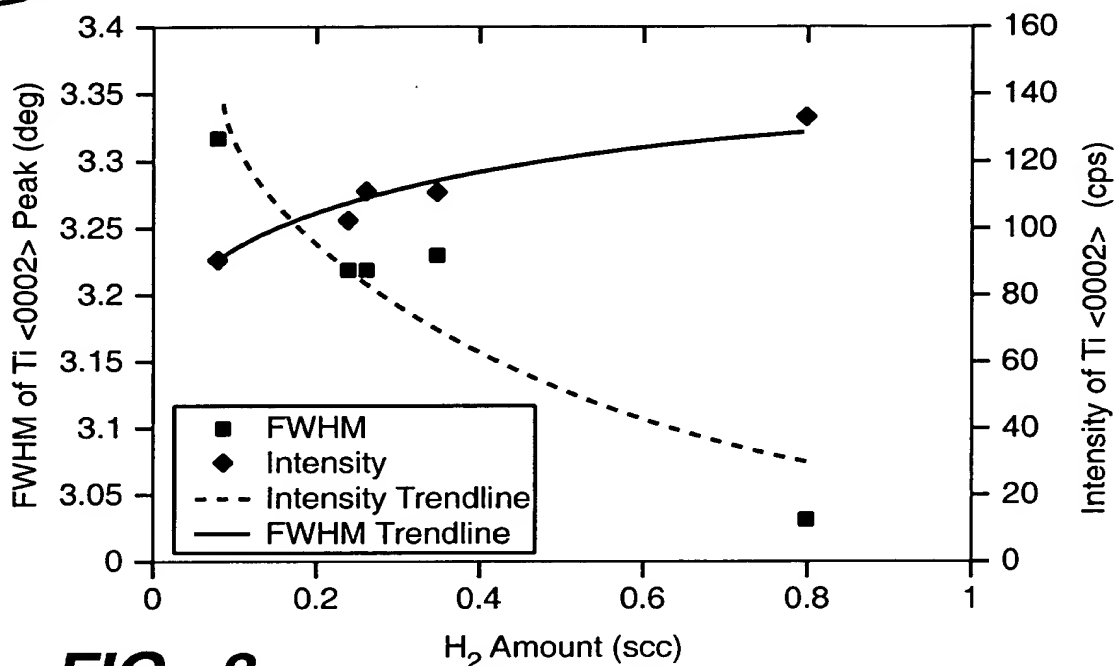Michael Rumer et al.
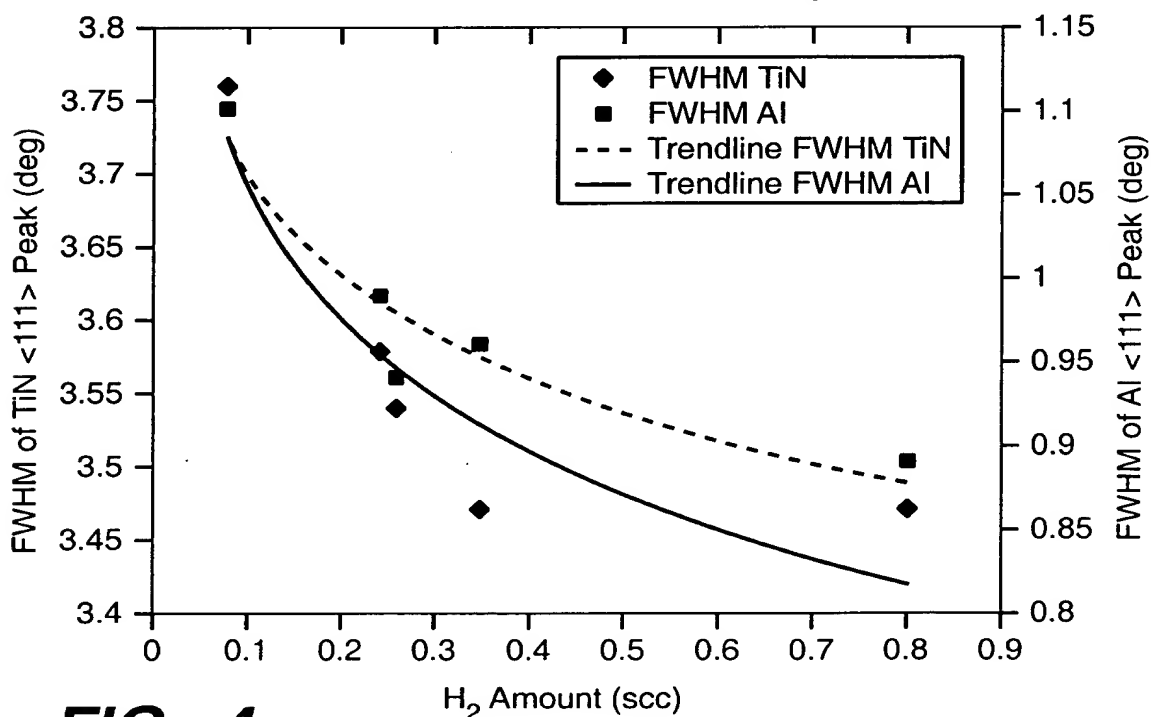Appln. No.: 09/675,627

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Ti <0002> Grain Performanc   vs. H₂ Amount
Introduced in Ti Module During Burst Step

FIG._3

TiN <111> and Al <111> Grain Performance vs. H₂
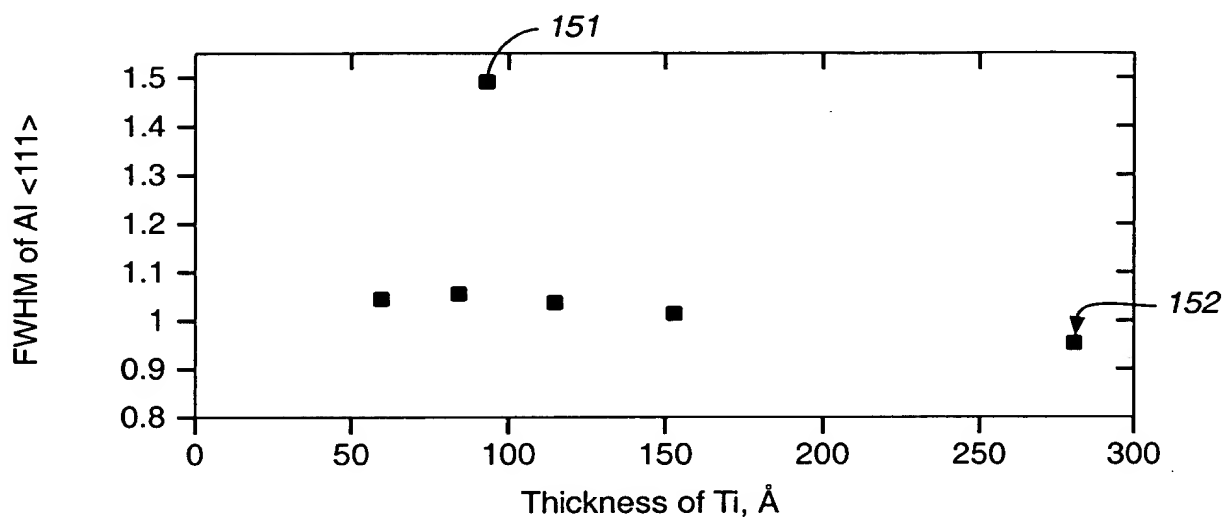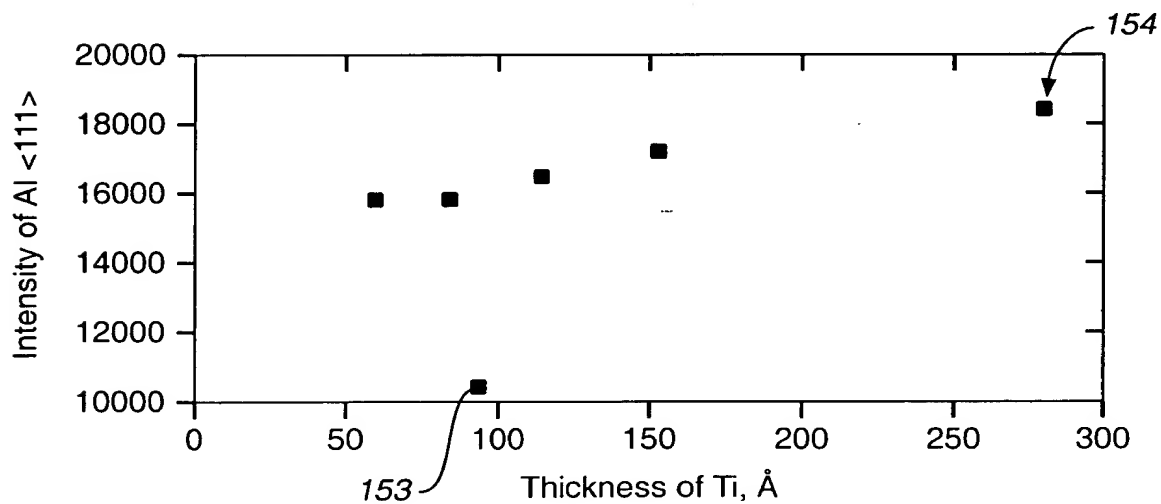**Amount Introduced in Ti Module During Burst Step**

FIG._4

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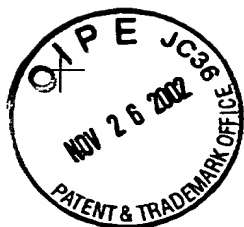
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FWHM of Al <111> P ak vs. Thickness of Ti Underlayer

FIG._5a

Intensity of Al <111> Peak vs. Thickness of Ti Underlayer

FIG._5b